

H263-S64-AAW1

DP 2U 4-Node High Density Server



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Features

- 2U 4-node rear access server system
- 4th Gen Intel® Xeon® Scalable Processors
- Intel® Xeon® CPU Max Series
- Dual processors, LGA4677
- 8-Channel RDIMM DDR5 per processor, 16 x DIMMs per node
- Supports Intel® Optane™ Persistent Memory 300 series
- Dual ROM Architecture supported
- 4 x Dedicated management ports
- 1 x CMC global management port
- 8 x 2.5" Gen4 NVMe/SATA hot-swappable bays
- 4 x M.2 with PCIe Gen4 x4 interface (optional)
- 4 x Low-profile PCIe Gen5 x16 expansion slots
- 4 x OCP 3.0 Gen5 x16 mezzanine slots
- Dual 3000W 80 PLUS Titanium redundant power supply

Specification

Dimensions	2U 4-Node - Rear access (W448 x H87.5 x D840 mm)	Rear I/O	Total: 8 x USB 3.2 Gen1, 4 x VGA, 4 x MLAN, 1 x CMC MLAN
Motherboard	MS63-HD1	Backplane I/O	PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
CPU	4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Intel® Xeon® Platinum Processor, Intel® Xeon® Gold Processor, Intel® Xeon® Silver Processor CPU TDP up to 225W	TPM	1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)
Socket	2 x LGA 4677 (Socket E) per node	Power Supply	Dual 3000W 80 PLUS Titanium redundant power supply Available for 2+1 redundant power supply configuration (optional) AC Input: 100-240V
Chipset	Intel® C741 Chipset	System Management	Aspeed® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Memory	Total 64 x DIMM slots (16 x DIMM slots per node) RDIMM modules up to 128GB supported 3DS RDIMM modules up to 256GB supported Memory speed: Up to 4800 MHz	OS Compatibility	Windows Server 2019 / 2011 RHEL 8.4 / 8.5 / 8.6 / 8.7 / 9.0 / 9.1 (x64) SLES 15 SP3 / 15 SP4 (x64) Ubuntu 22.04 LTS / 22.04.1 LTS (x64) VMware ESXi 7.0 Update 3i / 8.0
LAN	Total: 4 x Dedicated management ports 1 x 10/100/1000 CMC global management port	System Fans	4 x 80x80x80mm (16,500rpm)
Video	Integrated in Aspeed AST2600 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM Management chip on CMC board: Integrated in Aspeed AST2520A2-GP	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Storage	Total: 8 x 2.5" Gen4 NVMe/SATA hot-swappable bays SAS card is required for SAS devices support	Packaging Content	1 x H263-S64, 8 x CPU heatsinks, 1 x Rail kit, 24 x Carrier clips Packaging Dimensions: 1179 x 700 x 380 mm
RAID	Intel® SATA RAID 0/1/10/5	Reference Numbers	Barebone package: 6NH263S64DR000AAW1* - Motherboard: 9MS63HD1UR-000 - Rail kit: 25HB2-A66125-K0R - CPU heatsink: 25ST1-453200-A0R/25ST1-453208-C1R - M.2 extension riser card: 9CMTPO61NR-00 (optional) - Back plane board: 9CBPH081NR-00 - Ring topology kit: 6NH263S62S1000AAN11 (optional, QPA:1) - Power Supply: 25EPO-230009-L0S - C19 power cord 125V/15A (US): 25CP1-018000-Q0R (optional) - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R (optional)
Expansion Slots	Total: 4 x PCIe Gen5 x16 low-profile slots 4 x OCP 3.0 Gen5 x16 mezzanine slots *4 x M.2 slots (M-key, PCIe Gen4 x4, NGFF-2280/22110) *Optional kit for M.2 extension riser card		



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